printable, dielectric

TPC-X-PC-NC-HT-M/-E is a thixotropic thermally conductive phase changing compound optimising the thermal path e.g. between electronic packages and heat sinks. During warm-up the phase change compound starts filling up surface-specific roughnesses and unevenesses and expels any air enclosures from micro structures even at very low pressure. Both thin bondline and high thermal conductivity minimise the total thermal resistance. It can be pre-applied by screen printing. After drying the compound is dry-to-the-touch and ready for use on the thermal contact area. The compound is designed for applications with extended temperature requirements.

TPC-X-PC-NC-HT-M and TPC-X-PC-NC-HT-E are printable compounds with alternatively long and extended dry times. TPC-X-PC-NC-HT-E dries only at elevated temperature.



Release 03 / 2020

Technical Data Sheet

PROPERTIES

- Optimal thermal contact by thin bondline
- Silicone-free
- ☐ Thermal conductivity: 3.0 W/mK
- Dielectric
- Thixotropic
- Ideal alternative and replacement of messy thermal grease
- Accurate automated application by stencil printing
- for mass production
- TPC-X-PC-NC-HT-M med dry time:
- @ RT or elevated temp. ■ TPC-X-PC-NC-HT-E extended dry time:

only @ elevated temp.

AVAILABILITY

- TPC-X-PC-NC-HT-M and TPC-X-PC-NC-HT-E: Printable type med dry -M
- and extended dry -E E dries at elevated temperature only
- ☐ 360 ml SEMCO cartridges (transparent) ☐ 30 ml syringes

APPLICATION EXAMPLES

- Thermal link of: MOSFETs und IGBTs
- Memory Modules IGBT Power Modules
- CPUs
- For use in Servo drive control units / Computers / Automation appliances / Microelectronics

PROPERTY	UNIT	TPC-X-PC-NC-HT-M	TPC-X-PC-NC-HT-E
MATERIAL		Dryable Phase Change Compound	Dryable Phase Change Compound
Colour	•••••••••••••••••••••••••••••••••••••••	White	White
Assembly	••••••	~ Print	~ Print
Specific Gravity dried undried	g/cm³ g/cm³	1.1 @ RT 1.0 @ RT	1.10 @ RT 1.05 @ RT
Viscosity dried @ 10 rpm Viscosity undried @ 10 rpm	Pas Pas	65 @ 60°C / 38 @ 80°C / 25 @ 100°C / 18 @ 120°C 70	65 @ 60°C/38 @ 80°C/25 @ 100°C/18 @ 120°C 85
Drying @ Temperature @ Thickness	Time	@ 22°C: @ 60°C: @ 125°C: 24 h (0.05 mm) 24 min (0.05 mm) 4 min (0.05 mm) 48 h (0.15 mm) 53 min (0.15 mm) 6 min (0.15 mm) 56 h (0.25 mm) 56 min (0.25 mm) 10 min (0.25 mm)	6 60°C: 6 125°C: 4 h (0.05 mm) 10 min (0.05 mm) 12 h (0.15 mm) 15 min (0.15 mm) 20 h (0.25mm) 20 min (0.25 mm)
Storage (@ RT)	Months	9	9
RoHS Conformity	2015/863/EU	Yes	Yes
THERMAL			
Resistance¹ @ 150 PSI	°C-inch²/W	0.02	0.02
Resistance¹ @ 30 PSI	°C-inch²/W	0.03	0.03
Resistance¹ @ 10 PSI	°C-inch²/W	0.04	0.04
Thermal Conductivity	W/mK	3.0	3.0
Phase Change Temperature	°C	ca. 45	ca. 45
Operating Temperature Range	°C	< 140	< 140
Max. Storage Temp.	°C	25	25

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

